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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Coiltronics HCM1104 Series

High current power inductors



Product description

- High current carrying capacity
- Low core losses
- Magnetically shielded, low EMI
- Frequency range up to 5MHz
- Inductance range from 0.20 μ H to 10 μ H
- Current range from 7.5A to 45A
- 11.5x10.3mm footprint surface mount package in a 4.0mm height
- Powder iron core material
- Halogen free, lead free, RoHS compliant

Applications

- Voltage Regulator Module (VRM)
- Multi-phase regulators
- Point-of-load modules
- Desktop and server VRMs and EVRDs
- Base station equipment
- Notebook regulators
- Battery power systems
- Graphics cards
- Data networking and storage systems

Environmental data

- Storage temperature range (Component): -55°C to +125°C
- Operating temperature range: -55°C to +125°C (ambient + self-temperature rise)
- Solder reflow temperature: J-STD-020D compliant



Powering Business Worldwide



The Coiltronics brand of magnetics (formerly of the Bussmann Division of Cooper Industries) is now part of Eaton's Electrical Group, Electronics Division.

Coiltronics is now part of Eaton
Same great products plus even more.

Product specifications

Part Number ⁷	OCL ¹ (μ H) \pm 20%	FLL ² Min. (μ H)	I_{rms} ³ (amps)	I_{sat} ^{4,5} @25°C (amps)	DCR (m Ω) @ 20°C typical	DCR (m Ω) @ 20°C maximum	K-factor ⁶
HCM1104-R20-R	0.20	0.13	32	45	0.63	0.72	411
HCM1104-R36-R	0.36	0.23	30	42	1.04	1.20	269
HCM1104-R45-R	0.45	0.29	29	36	1.07	1.23	219
HCM1104-R56-R	0.56	0.36	25	32	1.56	1.80	230
HCM1104-R90-R	0.90	0.58	22	28	2.17	2.50	236
HCM1104-1R0-R	1.0	0.56	18	28	3.00	3.30	378
HCM1104-1R5-R	1.5	0.84	16	32	3.80	4.20	310
HCM1104-2R2-R	2.2	1.23	12	18	6.00	7.00	253
HCM1104-3R3-R	3.3	1.85	10	16	10.8	11.8	220
HCM1104-4R7-R	4.7	2.63	8.5	15	17.0	20.0	175
HCM1104-100-R	10	5.60	7.5	8.5	27.0	30.0	116

1. Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.25V_{rms}, 0.0Adc, +25°C.

2. Full Load Inductance (FLL) Test Parameters: 100kHz, 0.25V_{rms}, I_{sat} @ +25°C.

3. I_{rms} : DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.

4. I_{sat} : Peak current for approximately 20% rolloff at +25°C- HCM1104-R20-R to HCM1104-R90-R.

5. I_{sat} : Peak current for approximately 30% rolloff at +25°C- HCM1104-1R0-R to HCM1104-100-R.

6. K-factor: Used to determine B_{pp} for core loss (see graph). $B_{pp} = K * L * \Delta I$. B_{pp} : (Gauss), K: (K-factor from table), L: (Inductance in μ H), ΔI (Peak to peak ripple current in amps).

7. Part Number Definition: HCM1104-yyy-R

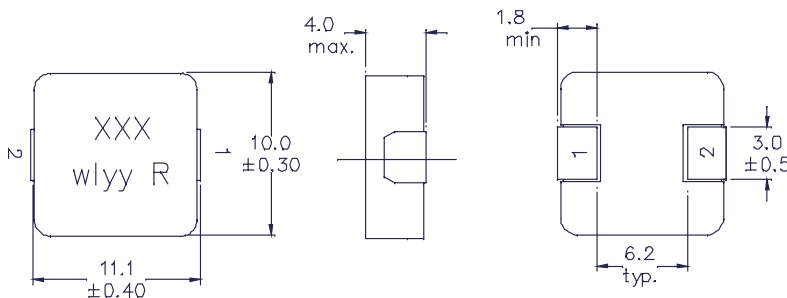
- HCM1104 = Product code and size

- yyy= Inductance value in μ H, R = decimal point,

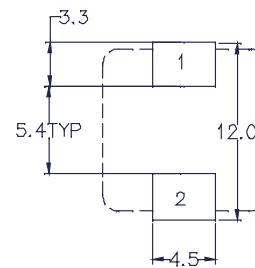
if no R is present then third character = number of zeros.

- "-R" suffix = RoHS compliant

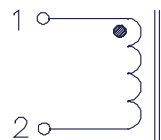
Dimensions - mm



Recommended pad layout



Schematic



Part marking: xxx = inductance value in μ H, R = decimal point, if no R is present, third character = number of zeros, wlyy = date code, R = revision level

All soldering surfaces to be coplanar within 0.10 millimeters

Tolerances are ± 0.3 millimeters unless stated otherwise

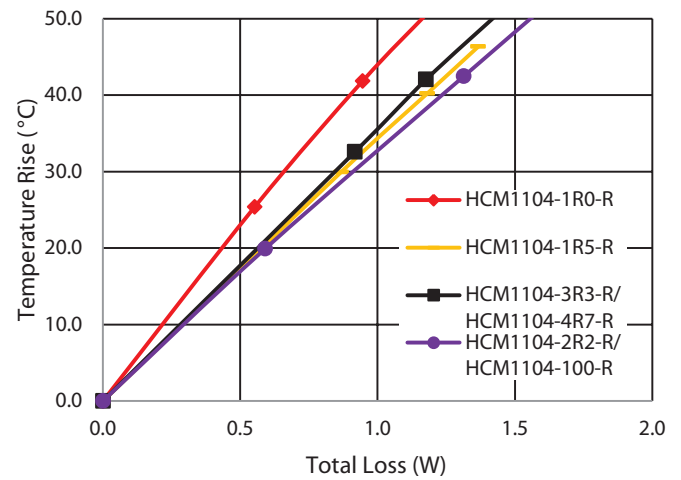
Color: Grey

Technical drawing of a multi-hole punch part. The drawing includes a side view on the left and a top view on the right. The side view shows a rectangular profile with a width of 4.2 and a height of 12.60. The top view shows a rectangular plate with a width of 24.0 (+/- 0.3) and a length of 16.00. The plate features a series of holes and slots. The holes are arranged in a row, with a diameter of 1.5 dia. The slots are rectangular, with a width of 5.60 and a height of 10.7. The distance between the centers of the holes is 4.0, and the distance between the centers of the slots is 2.0. The drawing also includes a section line A-A and a note indicating the user direction of feed.

SECTION A-A

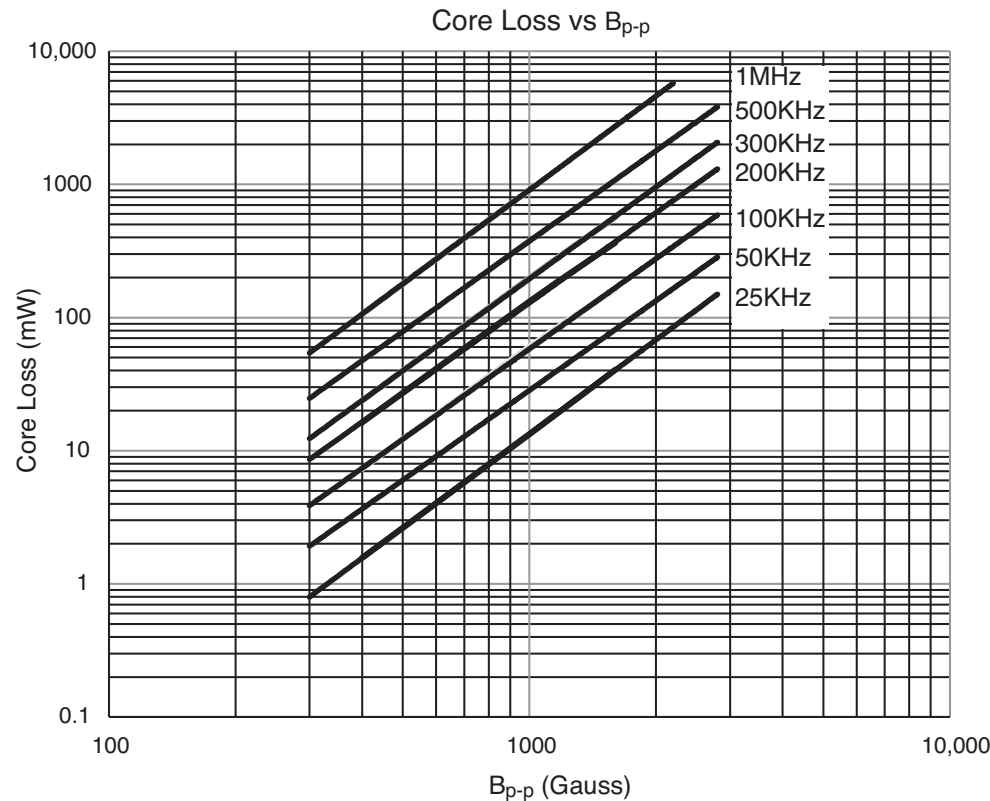
User direction of feed →

Temperature rise vs. total loss

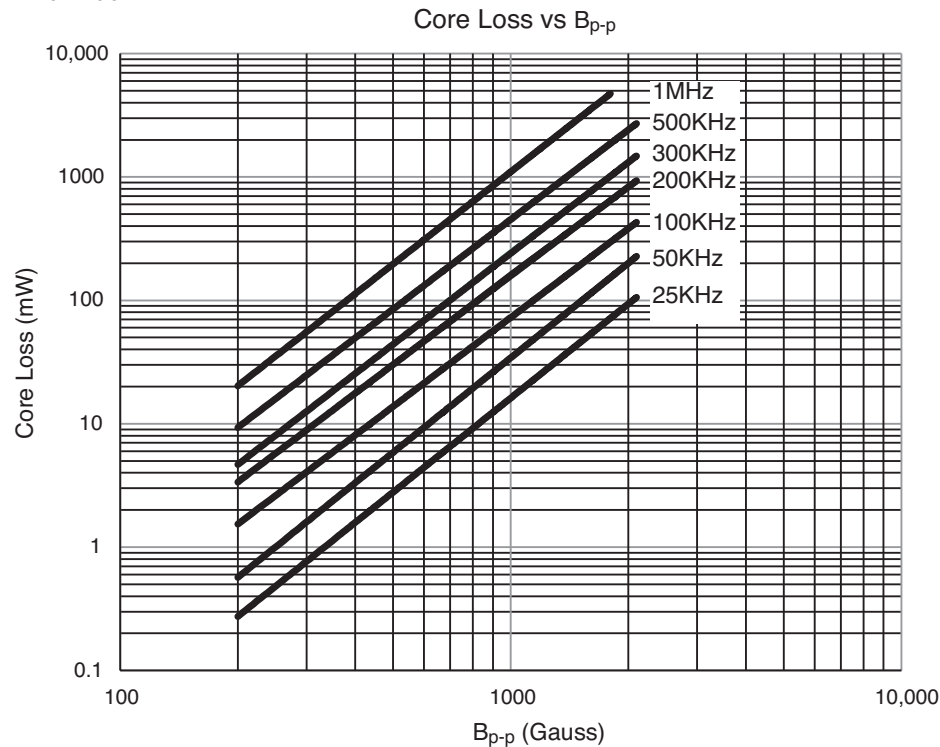


Core loss

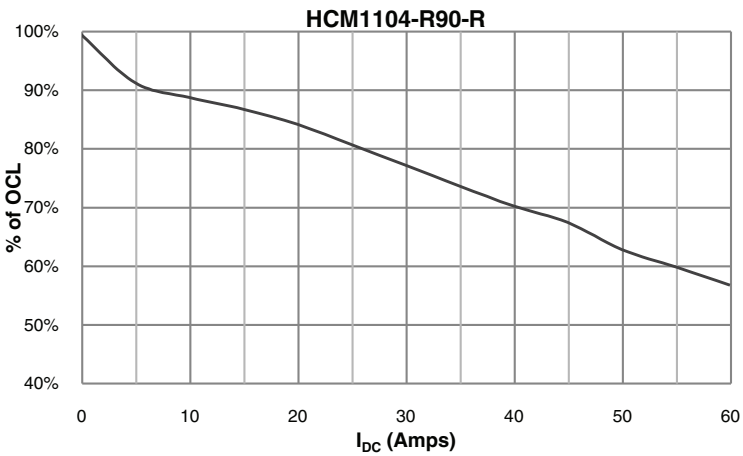
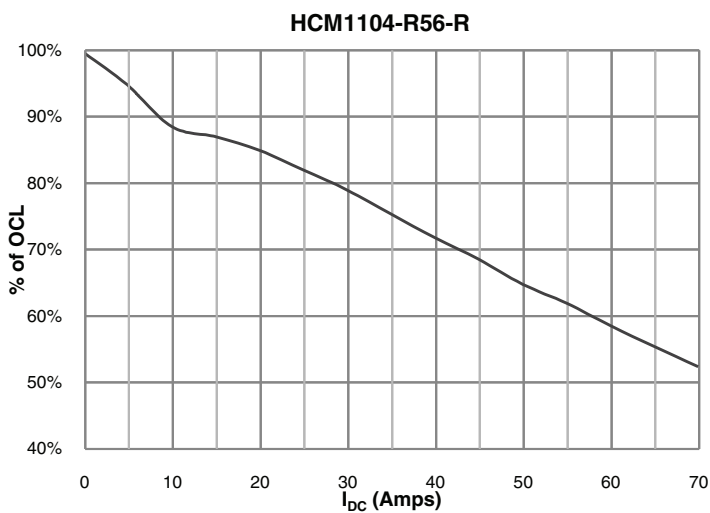
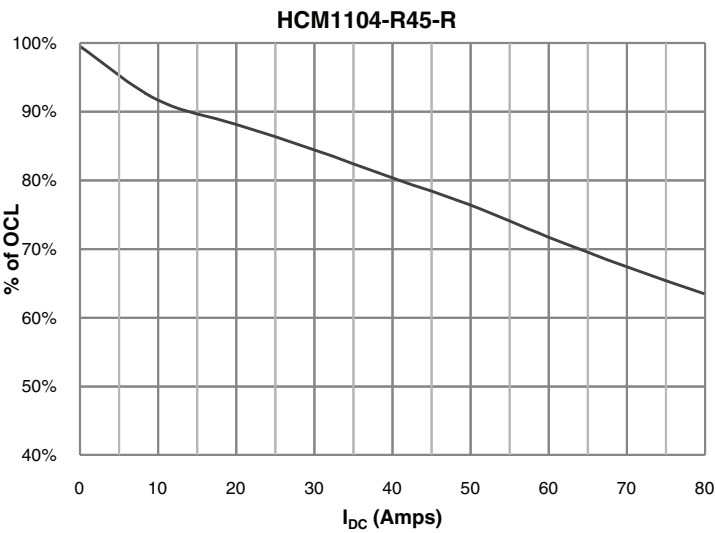
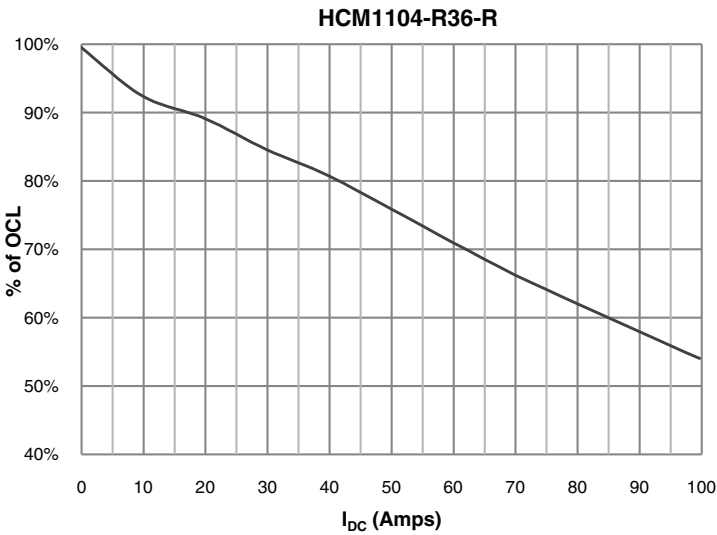
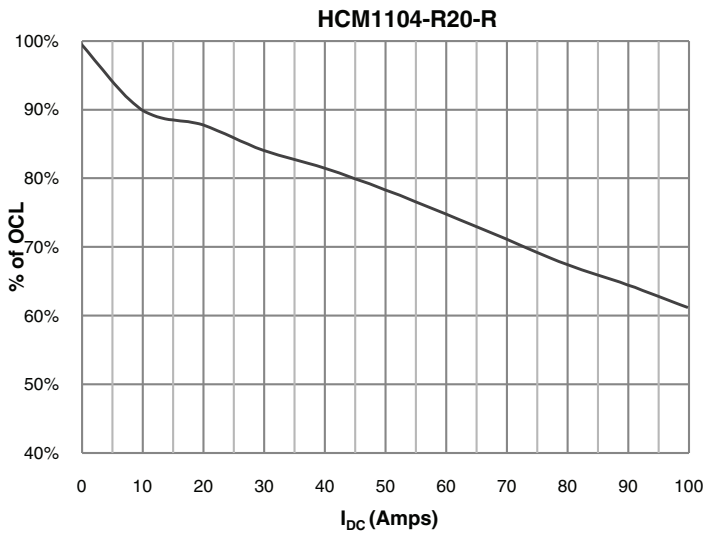
HCM1104-R20-R to HCM1104-R90-R



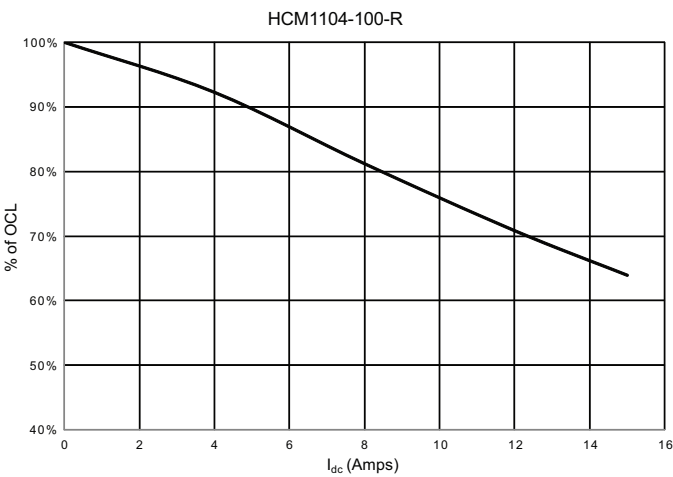
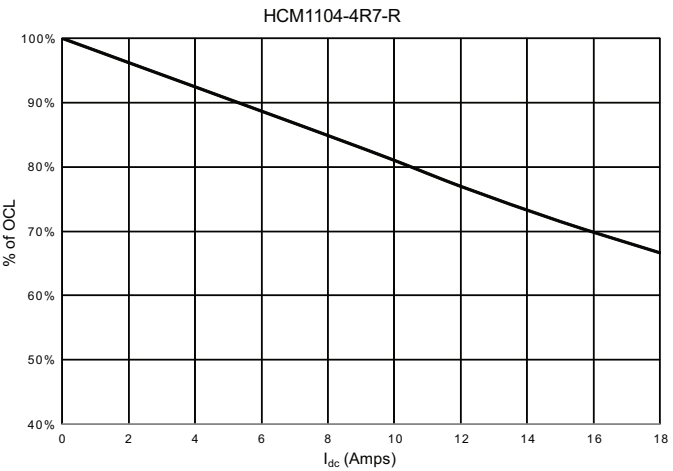
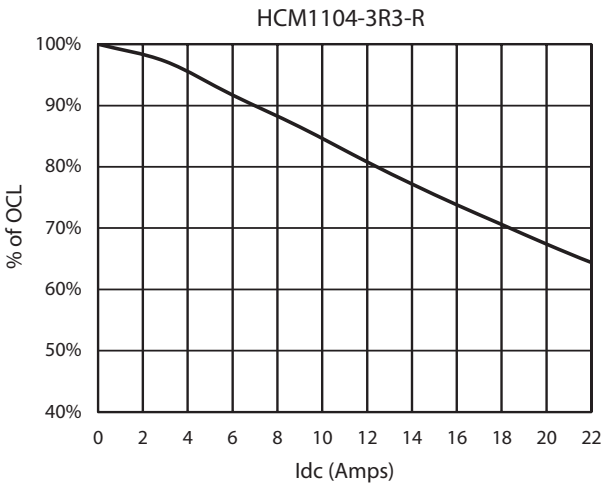
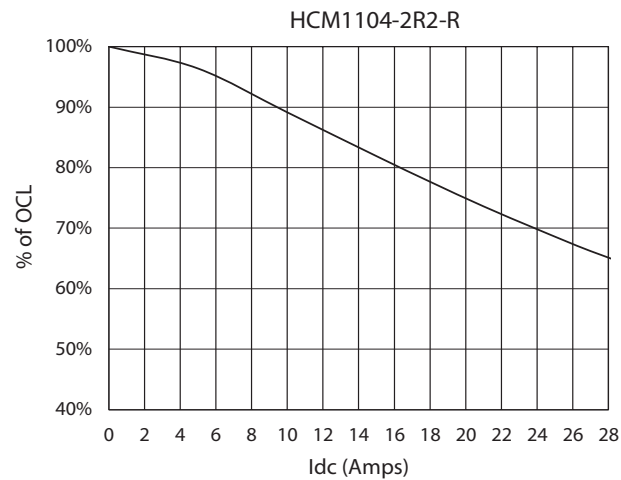
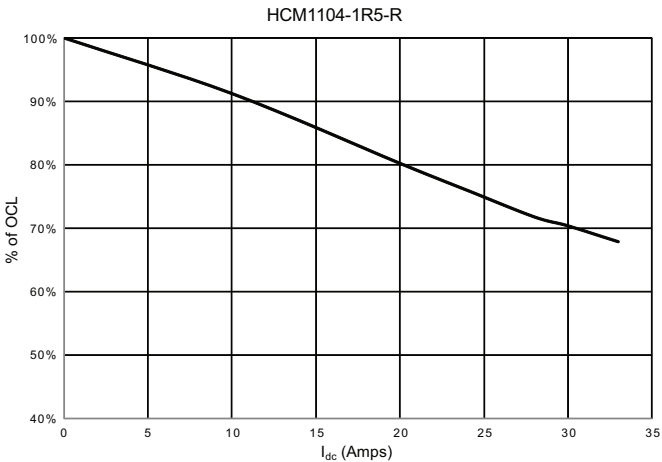
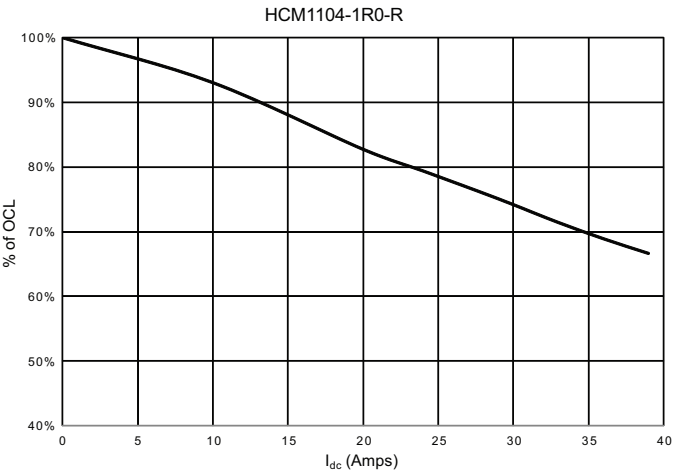
HCM1104-1R0-R to HCM1104-100-R



Inductance characteristics



Inductance characteristics



Solder reflow profile

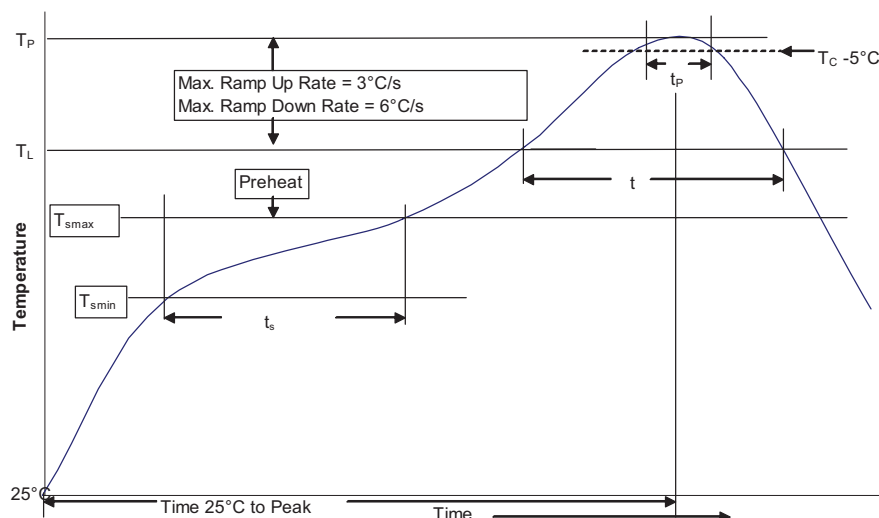


Table 1 - Standard SnPb Solder (T_c)

Package Thickness	Volume mm^3 <350	Volume mm^3 ≥ 350
<2.5mm	235°C	220°C
$\geq 2.5\text{mm}$	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_c)

Package Thickness	Volume mm^3 <350	Volume mm^3 350 - 2000	Volume mm^3 >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100°C	150°C
• Temperature max. (T_{smax})	150°C	200°C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

North America

Eaton's Electrical Group
Electronics Division
1225 Broken Sound Parkway NW
Suite F
Boca Raton, FL 33487-3533
Tel: 1-561-998-4100
Fax: 1-561-241-6640
Toll Free: 1-888-414-2645

Eaton's Electrical Group
Electronics Division
P.O. Box 14460
St. Louis, MO 63178-4460
Tel: 1-636-394-2877
Fax: 1-636-527-1607

Europe

Eaton's Electrical Group
Electronics Division
Burton-on-the-Wolds
Leicestershire, LE 12 5th UK
Phone: +44 (0) 1509 882 600
Fax: +44 (0) 1509 882 786

Eaton's Electrical Group
Electronics Division
Avda Santa Eulalia, 290
Terrassa, Barcelona 08223 Spain
Phone: +34-93-736-2813
Fax: +34-93-783-5055

Asia Pacific

Eaton's Electrical Group
Electronics Division
No.2, #06-01
Serangoon North Avenue 5
Singapore 554911
Tel: +65 6645 9888
Fax: +65 6728 3155

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**Eaton's Electrical Group
Electronics Division**
114 Old State Road
Ellisville, MO 63021
United States
www.eaton.com/elx



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